

III. CLAIM AMENDMENTS

1. (Currently amended) A method of manufacture of an electronic assembly—(8), the electronic assembly—(8) ~~comprising~~ having a circuit board and ~~ana~~ a first electrical component—(10), the method comprising ~~the steps of:~~

laying a first terminal of the first electrical component (10) upon a conductive region (12) of the circuit board, ~~and~~ i

providing solder paste (16) contacting the first terminal ~~of the component (10) and the circuit board;~~

~~the method being characterised by the steps of:~~
heating the solder paste (16) so as to liquefy the solder paste (16); ~~thereby~~ permitting a second terminal (18) of the first electrical component (10) to rise above the first terminal so as to erect the first electrical component (10) substantially perpendicular to the conductive region (12); and

curing the liquefied solder paste (16) in order to fix the first terminal ~~of the component (10) to the~~ conductive region (12) of the circuit board.

2. (Currently amended) A method according to Claim 1 further comprising ~~the step of:~~

electrically connecting the second terminal (18) ~~of the component (10) to a first~~ third terminal ~~of~~ coupled to an ~~electrical~~ electronic device (24).

3. (Currently amended) A method ~~as claimed in any one of the preceding claims~~according to claim 1, wherein the second terminal ~~(18) of the component (10)~~ is gold plated.

4. (Currently amended) A method as claimed in Claim 2 ~~or Claim 3~~, wherein the electronic device ~~(24)~~ is an integrated circuit.

5. (Currently amended) A method as claimed in Claim 2 ~~or Claim 3~~, wherein the electronic device ~~(24)~~ is a second electrical component.

6. (Currently amended) An electronic assembly ~~(8)~~ comprising:

a conductive region ~~(12)~~, i and

a first electrical component ~~(10)~~ having a first terminal at a first end and a second terminal ~~(18)~~ at a second end, the first terminal being fixed to the conductive region ~~(12)~~ and the second terminal ~~(12)~~ being disposed substantially perpendicular to the conductive region,

~~characterised in that,~~

wherein the second terminal ~~(12)~~ is arranged to receive a connecting means ~~(20)~~ for facilitating an electrical connection between the first electrical component ~~(10)~~ and an electronic device ~~(24)~~.

7. (Currently amended) An electronic assembly ~~(8)~~ as claimed in Claim 6, wherein the second terminal ~~(18) of the component (10)~~ is gold plated.

8. (Currently amended) An electronic assembly (8) as claimed in Claim 6 ~~or Claim 7~~, wherein the connecting means ~~(20)~~ is a wire bond.

9. (Currently amended) An electronic assembly (8) as claimed in ~~any one of the claims 6 to 8~~ claim 6, wherein the electronic device ~~(24)~~ is an integrated circuit or ~~ana~~ second electrical component.

10. (Currently amended) ~~A use of tombstoning in a method of manufacture of an electronic assembly (8). A~~ method of manufacture of an electronic assembly comprising:

laying a first terminal of an electrical component of the assembly upon a conductive region of a circuit board of the assembly;

providing solder paste contacting the first terminal and the circuit board; and

utilizing tombstoning to position the electrical component on the circuit board.